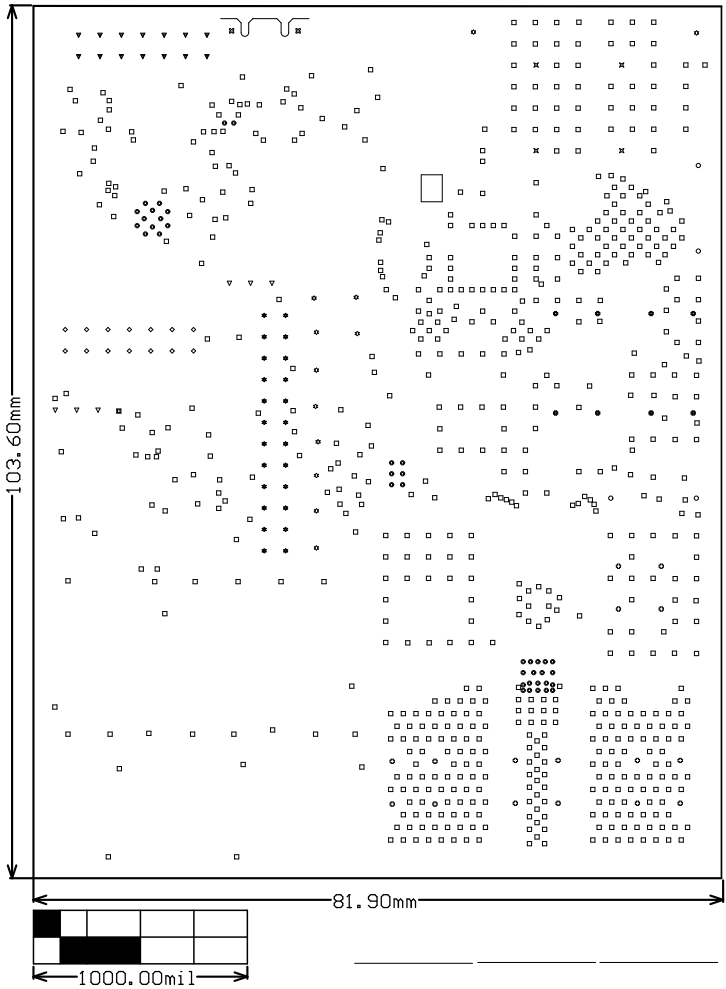


Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
⊙	39	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
□	692	13.78mil (0.350mm)	PTH	Round	Top Layer - Bottom Layer	
▣	1	17.72mil (0.450mm)	PTH	Round	Top Layer - Bottom Layer	
⊕	8	35.43mil (0.900mm)	PTH	Round	Top Layer - Bottom Layer	
◇	14	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
▽	6	40.16mil (1.020mm)	PTH	Round	Top Layer - Bottom Layer	
☆	24	40.16mil (1.020mm)	PTH	Round	Top Layer - Bottom Layer	+/-3.15mil
▼	14	43.31mil (1.100mm)	PTH	Round	Top Layer - Bottom Layer	+/-1.97mil
○	4	51.18mil (1.300mm)	PTH	Round	Top Layer - Bottom Layer	
⊕	16	62.99mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	+3.94mil/-0.00mil
✕	4	62.99mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	
☆	12	63.00mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	2	23.62mil (0.600mm)	PTH	Slot	Top Layer - Bottom Layer	
	836 Total					

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout



Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.5	
1	Top Layer		2.80mil		
	Dielectric 1	FR4 370	11.40mil	4.2	
2	Signal Layer 1		1.40mil		
	Dielectric 2	FR4 370	30.00mil	4.2	
3	Signal Layer 2		1.40mil		
	Dielectric 3	FR4 370	11.40mil	4.2	
4	Bottom Layer		2.80mil		
	Bottom Solder	Solder Resist	0.40mil	3.5	
	Bottom Overlay				

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL

MIN. CLEARANCE: 0.2 mm

MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNUAL RING: 0.05mm (2MIL) EXTERNAL

PER: PC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL HOLES +/- 3 MIL

HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:

FR-408

☒ FR-4 High Tg

OTHER

THICKNESS: ☒ 62 MIL (1.6mm) +/-10%

OTHER

TOLERANCE: ☒ ANS PC-6012 TYPE 3 CLASS 2

OTHER +/-

BOW & TWIST: ☒ ANS PC-6012 TYPE 3 CLASS 2

OTHER +/-

DILLING:

REFERENCE: ☒ AS SHOWN

☒ NO_DRILL_FILES

PTH COPPER THICKNESS: ☒ 20-30 um

OTHER

BOARD FINISH:

SULFORED: ☒ TOP

☒ BOTTOM

SULFORED COLOR: ☒ WHITE

OTHER

SOLDER RESIST COLOR: ☒ GREEN

OTHER

☒ MATTE

SEM-GLOSS

SURFACE FINISH:

☒ IMMERSION GOLD (ENIG)

ENIG

☐ MIL TIN/SILVER OR EQUIV

OTHER

ARRAY/PANEL:

☐ CUT AND TRIM PER MH BOARD OUTLINE

☐ NO ROUTE

☒ V-Score

CERTIFICATION:

MATERIALS AND WORKMANSHIP FOR ALL POBS TO MEET OR EXCEED THE REQUIREMENTS OF:

☒ ANS PC-A-800F CLASS ->

☐ 1

☒ 2

☐ 3

☒ RoHS

OTHER

PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.

PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:

MICROSECTION: ☐ YES

BAKE BOARD ELEC. TEST: ☐ NONE

☒ REQUIRED

PER ORDER

☐ XX MIL VAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE

XX MIL VAS REQUIRE CONDUCTIVE FILL AND PLANARIZE

OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE

LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE



PROJECT TITLE:
DRV8263S-4H-GIEVM_V0F0N

DESIGNED FOR:
Public Release

FILE NAME:
H0093ET_DRV8263S-GIEVM_V0F0N_PcbDoc

ENGINEER:
Jacob Thompson

LAYOUT BY:
Jacob Thompson

SCALE: 1:12

ALTIM DESIGNER VERSION:
24.6.1.21